

GaAs INTEGRATED CIRCUIT μ PG2162T5N

DPDT SWITCH FOR 2.4 GHz AND 6 GHz DUAL-BAND WIRELESS LAN

DESCRIPTION

The μ PG2162T5N is a GaAs MMIC DPDT (<u>D</u>ouble <u>P</u>ole <u>D</u>ouble <u>T</u>hrow) switch which was developed for 2.4 GHz and 6 GHz dual-band wireless LAN. This device can operate frequency from 2.4 GHz band and 6 GHz band, having the low insertion loss and high isolation.

This device is housed in a 6-pin plastic TSON (\underline{T} hin \underline{S} mall \underline{O} ut-line \underline{N} on-leaded) package. And this package is able to high-density surface mounting.

FEATURES

Operating frequency
 If = 2.4 to 2.5 GHz and 4.9 to 6.0 GHz
 Switch control voltage
 Vcont (H) = 2.8 to 5.0 V (3.0 V TYP.)
 Vcont (L) = -0.3 to 0.3 V (0 V TYP.)
 Low insertion loss
 Lins1 = 0.60 dB TYP. @ f = 2.4 to 2.5 GHz, Vcont (H) = 3.0 V, Vcont (L) = 0 V
 Lins2 = 0.85 dB TYP. @ f = 4.9 to 6.0 GHz, Vcont (H) = 3.0 V, Vcont (L) = 0 V
 High isolation
 ISL3 = 30 dB TYP. @ f = 2.4 to 2.5 GHz, Vcont (H) = 3.0 V, Vcont (L) = 0 V
 ISL4 = 27 dB TYP. @ f = 4.9 to 6.0 GHz, Vcont (H) = 3.0 V, Vcont (L) = 0 V

• Handling power : $P_{in (1 dB)} = +31.0 dBm TYP$. @ f = 2.5 GHz, $V_{cont (H)} = 3.0 V$, $V_{cont (L)} = 0 V$: $P_{in (1 dB)} = +29.0 dBm TYP$. @ f = 6.0 GHz, $V_{cont (H)} = 3.0 V$, $V_{cont (L)} = 0 V$

• High-density surface mounting: 6-pin plastic TSON package (1.5 × 1.5 × 0.37 mm)

APPLICATIONS

• Dual-band wireless LAN (IEEE802.11a + b/g)

ORDERING INFORMATION

Part Number	Order Number	Package Marking Supplying Form		Supplying Form
μPG2162T5N-E2	μPG2162T5N-E2-A	6-pin plastic TSON (Pb-Free)	G5A	Embossed tape 8 mm wide Pin 1, 6 face the perforation side of the tape Qty 3 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office.

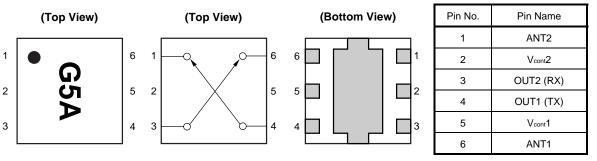
Part number for sample order: μPG2162T5N-A

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

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PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Remark Exposed pad : GND

TRUTH TABLE

V _{cont} 1	V _{cont} 2	ANT1-OUT1 (TX)	ANT1-OUT2 (RX)	ANT2-OUT1 (TX)	ANT2-OUT2 (RX)
High	Low	OFF	ON	ON	OFF
Low	High	ON	OFF	OFF	ON

ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Switch Control Voltage	Vcont	-6.0 to +6.0	V
Input Power	Pin	+32	dBm
Operating Ambient Temperature	TA	-45 to +85	°C
Storage Temperature	T _{stg}	-55 to +135	°C

RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Switch Control Voltage (H)	V _{cont (H)}	2.8	3.0	5.0	V
Switch Control Voltage (L)	V _{cont (L)}	-0.3	0	0.3	V
Operating Frequency 1	f1	2.4	-	2.5	GHz
Operating Frequency 2	f2	4.9	-	6.0	GHz

ELECTRICAL CHARACTERISTICS

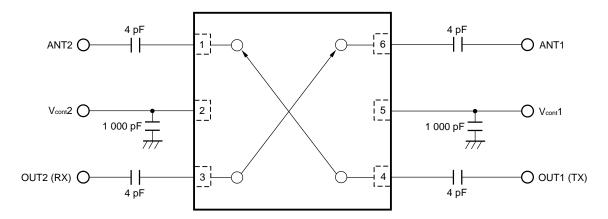
(TA = +25°C, V_{cont} (H) = 3.0 V, V_{cont} (L) = 0 V, Z₀ = 50 Ω , DC blocking capacitors = 4 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	Lins1	f = 2.4 to 2.5 GHz	-	0.60	0.85	dB
Insertion Loss 2	Lins2	f = 4.9 to 6.0 GHz	-	0.85	1.10	dB
Isolation 1 (ANT to OUT)	ISL1	f = 2.4 to 2.5 GHz	30	35	-	dB
Isolation 2 (ANT to OUT)	ISL2	f = 4.9 to 6.0 GHz	30	34	-	dB
Isolation 3 (ANT1 to ANT2, TX to RX)	ISL3	f = 2.4 to 2.5 GHz	27	30	-	dB
Isolation 4 (ANT1 to ANT2, TX to RX)	ISL4	f = 4.9 to 6.0 GHz	24	27	-	dB
Input Return Loss 1	RLin1	f = 2.4 to 2.5 GHz	-	15	-	dB
Input Return Loss 2	RLin2	f = 4.9 to 6.0 GHz	-	15	-	dB
Output Return Loss 1	RLout1	f = 2.4 to 2.5 GHz	-	15	-	dB
Output Return Loss 2	RLout2	f = 4.9 to 6.0 GHz	-	15	-	dB
1 dB Loss Compression Input Power 1 Note	Pin (1 dB) 1	f = 2.4 to 2.5 GHz	-	+31.0	-	dBm
1 dB Loss Compression Input Power 2 Note	Pin (1 dB) 2	f = 4.9 to 6.0 GHz	-	+29.0	-	dBm
Input 3rd Order Distortion Intercept Point	IIP3	f1 = 2 500 MHz, f2 = 2 501 MHz, P _{in} (1 tone) = +20 dBm	-	+50	ı	dBm
Switch Control Current	Icont		-	0.1	1.0	μА
Switch Control Speed	tsw	50% CTL to 90/10%	-	150	ı	ns

Note Pin (1 dB) is measured the input power level when the insertion loss increases more 1 dB than that of linear range.

Caution This device is used it is necessary to use DC blocking capacitors.

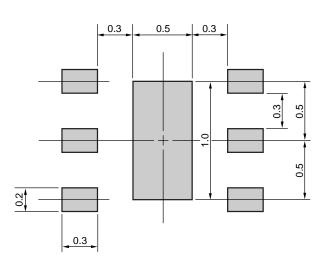
EVALUATION CIRCUIT



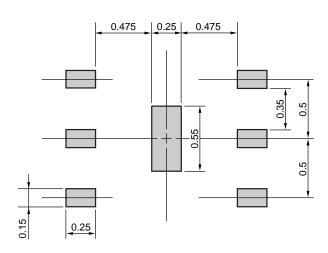
The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

MOUNTING PAD AND SOLDER MASK LAYOUT DIMENSIONS 6-PIN PLASTIC TSON (UNIT: mm)

MOUNTING PAD



SOLDER PAD

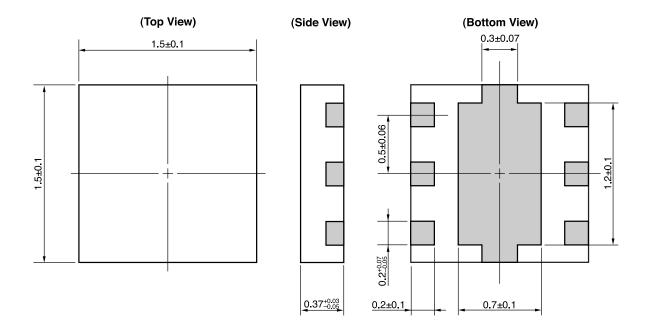


Solder thickness: 0.08 mm

Remark The mounting pad and solder mask layouts in this document are for reference only.

PACKAGE DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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M8E 02.11-1

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

NEC Compound Semiconductor Devices Hong Kong Limited

E-mail: contact@ncsd-hk.necel.com

 Hong Kong Head Office
 TEL: +852-3107-7303
 FAX: +852-3107-7309

 Taipei Branch Office
 TEL: +886-2-8712-0478
 FAX: +886-2-2545-3859

 Korea Branch Office
 TEL: +82-2-558-2120
 FAX: +82-2-558-5209

NEC Electronics (Europe) GmbH http://www.eu.necel.com/

TEL: +49-211-6503-0 FAX: +49-211-6503-1327

California Eastern Laboratories, Inc. http://www.cel.com/

TEL: +1-408-988-3500 FAX: +1-408-988-0279

Compound Semiconductor Devices Division NEC Electronics Corporation URL: http://www.ncsd.necel.com/



4590 Patrick Henry Drive Santa Clara, CA 95054-1817 Telephone: (408) 919-2500

Facsimile: (408) 988-0279

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This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

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Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
PBB	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

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